micromachines

an Open Access Journal by MDPI

IMPACT FACTOR 3.4

Indexed in: PubMed

CITESCORE 4.7

Wafer Level Packaging of MEMS

Guest Editor:

Prof. Dr. Shuji Tanaka
Department of Robotics,
Graduate School of Engineering,
Tohoku University 6-6-01 Aramaki
Aza Aoba, Aoba-ku, Sendai,
Miyagi 980-8579, Japan

Deadline for manuscript submissions:
closed (15 March 2018)

Message from the Guest Editor

Packaging is essential for the practical use of MEMS, in terms of performance and reliability. The electronics market has been continuously requiring the downsizing and cost reduction of MEMS, and, thus, wafer-level packaging is becoming more important and replacing conventional die-level packaging. One of important features of the wafer-level packaging of MEMS is that it often needs the device cavity, which is hermetically sealed. Therefore, hermetic/vacuum sealing and electrical feedthrough from the sealed cavity are key technologies. On the other hand, emerging devices need new types of packaging, for example, biocompatible and flexible packaging, which are also attracting a great deal of attention. Test, reliability control, wiring, dicing, chip-level integration and material development related to the wafer-level packaging of MEMS are also included in the scope of this Special Issue. Wafer-level packaging is strongly connected to the integration of multiple components, and, thus, papers about wafer-level integration are also welcome.

mdpi.com/si/11090

Special Issue

micromachines

IMPACT FACTOR 3.4 | Indexed in: PubMed | CITESCORE 4.7

an Open Access Journal by MDPI

Editor-in-Chief

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.
High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.
Journal Rank: JCR - Q2 (*Chemistry, Analytical*) / CiteScore - Q2 (*Mechanical Engineering*)

Contact Us

Micromachines Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/micromachines
micromachines@mdpi.com
𝕏@micromach_mdpi